

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SANG JUN YOUN	11/24/2006
HO GAB JEONG	11/24/2006
RECEIVING PARTY DATA	
Name:	SAMBARK CO., LTD.
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City:	ASAN-SI
State/Country:	KOREA, REPUBLIC OF
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13049700
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NAME OF SUBMITTER:	J. ROBERT BROWN, JR.
SIGNATURE:	/J. Robert Brown, Jr./
DATE SIGNED:	09/04/2018
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, I, among the following inventors, am an inventor of **“Thermoplastic Compound Plate-Shaped Material, Method for Manufacturing and Articles Manufactured Using the Same”** (the “Invention”), described in an application for Letters Patent of the United States of America filed on September 29, 2006, Application No. 10/599,523 or, if not identified here by filing date and application number, executed by me on even date with my execution of this Assignment;

WHEREAS, Sambark Co., Ltd., a corporation created and existing under and by virtue of the laws of the Republic of Korea, is desirous of acquiring the entire right, title and interest in and to the aforesaid Invention throughout the world, and all right, title and interest in, to and under any and all Letters Patent of the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell, assign, transfer and set over to Sambark Co., Ltd., all right, title and interest in and to the said Invention throughout the world, and said application for U.S. Letters Patent, and any and all other applications for said Invention, including divisional, continuation, provisional, non-provisional, regular, and reissue applications, and any and all Letters Patent of the United States and foreign countries which may be granted therefor, the same to be held and enjoyed by Sambark Co., Ltd. for its own use and benefit, and for the use and benefit of its successors, assigns, or other legal representatives, to the end of the term or terms for which said Letters Patent of the United States or foreign countries are or may be granted or reissued, as fully and entirely as the same would have been held and enjoyed if this assignment and sale had not been made.


And I hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all Letters Patent of the United States on said Invention or resulting from said application and from any and all divisions, continuations, and reissues thereof, to Sambark Co., Ltd., as assignee of my entire interest, and hereby covenant that I have the full right to convey the entire interest herein assigned, and that I have not executed and will not execute any agreement in conflict herewith.

And I further hereby covenant and agree that I will, at any time, upon request, execute and deliver any and all papers that may be necessary or desirable to perfect the title of said Invention and to such Letters Patent as may be granted therefor, to Sambark Co., Ltd., its successors, assigns, or other legal representatives and that if Sambark Co., Ltd. its successors, assigns or other legal representatives shall desire to file any divisional or continuation applications or to secure a reissue of such Letters Patent, or to file a disclaimer relating thereto, I will upon request, sign all papers, make all rightful oaths and do all lawful acts requisite for the filing of such divisional or continuation application, or such application for reissue and the procuring thereof, and for the filing of such disclaimer, without further compensation but at the expense of said assignee, its successors, or other legal representatives.

And I do further covenant and agree that I will, at any time upon request, communicate Sambark Co., Ltd., its successors, assigns or other legal representatives, such facts relating to said Invention and Letters Patent or the file history thereof as may be known to us, and testify as to the same in any interference or other litigation when requested so to do, without further compensation but at the expense of said assignee, its successors, or other legal representatives.


ASSIGNOR:

Date: Nov. 24, 2006

Signature: 
Sang Jun YOUN


WITNESS:

Date: Nov. 24, 2006

Signature: 
Name: JUNG, mi Jung


ASSIGNOR:

Date: Nov. 24, 2006

Signature: 
Ho Gab JEONG

WITNESS:

Date: Nov. 24, 2006

Signature: 
Name: JUNG, mi Jung